Product Bulletin: GenSolve™ 365
Isoprene Negative Resist and Residue Remover

Advantages:
- Successfully demonstrated on cyclized isoprene negative photoresists such as Fujifilm HNR (80, 120) and SC(100, 180, 450, and 900) resists,
- Especially effective on resists cured to excessive temperatures > 200ºC
- Complete removal of residual negative-resist residue after ash processing
- Rapid stripping at 60ºC to 70ºC of fully cured isoprene negative photoresists.
- Is stable for a range of temperatures up to 120ºC
- Immersion tool process times: typically 30 minutes (bulk resist removal)
- Spray tool process times: 30 – 45 minutes
- Low etch rates of Aluminum, Titanium, and Titanium Nitride
- No etch rates of common dielectrics
- Reduced cost of ownership due to long bath life
- Non toxic

Process Results:

Unprocessed

GenSolve 365, 20 Minutes, 75ºC
Static Immersion Processing

Post Etch, Pre Resist Strip

GenSolve 365, 20 Minutes, 75ºC

SC180 Negative-tone photoresist removal, Au/Al Pattern on Dielectric

Metal Compatibility in GenSolve 365

Time in Minutes at 75ºC

Angstroms

Al
Ti/W
Cu

0 50 100 150

0 1000 2000 3000 4000 5000 6000 7000 8000
Process Results: (Continued)

Aluminum Surface Cleanliness

Product Design
- GenSolve 365 is a single formulation product that is not modified for specific uses. This product is designed to swell and dissolve Isoprene Negative Resist resins along with all PACs that may be present. Bulk resist films or post-ash residues can be stripped in static bath, immersion, batch or single-wafer spray tools.

Immersion-Tool Process Flow

Spray-Tool Process Flow

Additional Information

Product Handling: Keep container closed when not in use. Refer to Material Safety Data Sheet for safe handling guidelines.

Storage: Store in a well-ventilated area, in original containers. Keep away from strong oxidizing or reducing agents.

Shelf Life: 2 years

Physical Properties: APPEARANCE: Dark brown liquid, SPECIFIC GRAVITY: 0.98 @ 68F, SOLUBILITY IN WATER (weight %): 100% - Miscible, BOILING POINT: >165C.

Material Compatibility: Following materials of construction are compatible with GenSolve™ 365: Polypropylene and Poly Olefins, Polyethylene (low and high density), Teflon®, Butyl Rubber, Teflon encap silicone, Chemraz®, AFLAS®, and 316L Stainless steel.

GenSolve is a trademark of KMG Electronic Chemicals Inc. All rights reserved. Teflon is a registered trademark of E.I. duPont de Nemours and Company. Chemraz is a registered trademark of Greene, Tweed & CO. AFLAS is a registered trademark of the Asahi Glass Co., Ltd.

The information given herein is based on data believed to be reliable, but KMG Electronic Chemicals, Inc., makes no warranties, expressed or implied, as to its accuracy and assumes no liability arising out of its use by others. This publication is not to be taken as a license to operate under, or recommendation to infringe upon any patent.